(54) SENSOR MODULE

(71) Applicant: Samsung Electronics Co., Ltd., Suwon-si, (KR)

(72) Inventors: Sheldon George Phillips, Glendale, CA (US); Frank Nuovo, Los Angeles, CA (US); Tom Torfs, Kranem (BE); Lindsay Brown, Mierlo (NL)

(73) Assignee: Samsung Electronics Co., Ltd., Suwon-si, Gyeonggi-do (KR)

(**) Term: 14 Years

(21) Appl. No.: 29/491,668

(22) Filed: May 22, 2014

(51) LOC (10) Cl. ........................................... 10-04

(52) U.S. Cl.

USPC .................................................. D10/103, D11/3

(58) Field of Classification Search

CPC ...................... G08G 1/096883; G08G 1/096872; G08G 1/096775; G01C 21/16; G01C 21/3688; G01C 21/30; G01V 8/20; G01J 5/02; G01J 5/023; G01J 5/24; G01J 5/10; G01J 5/20; G01J 5/0235; G01J 5/08; G01J 5/0853; G01J 5/33; G01J 5/34

USPC .............. D10/30-39, 65, 70, 78, 97, 98, 103; D11/3; D13/173-177; D14/138 R, D14/203.5, 247, 338-340, 344, 346, 347; D24/167, 168

See application file for complete search history.

(56) References Cited

U.S. PATENT DOCUMENTS

D305,422 S * 1/1990 Steer et al. .................. D14/247
D331,020 S * 11/1992 Ishii et al. ............... D10/31
D528,439 S * 9/2006 Burton ..................... D10/32
D528,928 S * 9/2006 Burton ..................... D10/38
D536,265 S * 2/2007 Reymoss .................... D10/31
D538,687 S * 3/2007 Komlauensaen .......... D10/70

D560,520 S * 1/2008 Oberrieder et al. .......... D10/65
D569,282 S * 5/2008 Daniel ...................... D10/65
D573,905 S * 7/2008 Poirier ...................... D10/65
D610,476 S * 2/2010 Daniel ...................... D10/65
D670,583 S * 11/2012 Shaaman .................. D10/70
D672,667 S * 12/2012 Mix ....................... D10/65

* cited by examiner

Primary Examiner — Antoine D Davis

Attorney, Agent, or Firm — McAndrews Held & Malloy, Ltd.

(57) CLAIM

The ornamental design for a sensor module, as shown and described.

DESCRIPTION

This application makes reference to:

The above referenced application, and all of the subject matter disclosed therein, is incorporated herein by reference in its entirety.

FIG. 1 is a top left front perspective view of a sensor module showing our new design;

FIG. 2 is a rear elevation view thereof;

FIG. 3 is a front elevation view thereof;

FIG. 4 is a right side elevation view thereof;

FIG. 5 is a left side elevation view thereof;

FIG. 6 is a top plan view thereof;

FIG. 7 is a bottom plan view thereof;

FIG. 8 is a bottom right rear perspective view thereof; and,

FIG. 9 is an enlarged view of the portion encircled in FIG. 1. The dashed broken lines are for environmental purposes only and form no part of the claimed design.

The dashed broken lines in FIG. 1 labeled with the number "9" encircle a portion of the claimed design that is illustrated in an enlargement in FIG. 9.

Any views of the sensor module that are not shown in the figures form no part of the claimed design.

1 Claim, 5 Drawing Sheets